

TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type ( $\pi$ -MOS V)

# 2SJ680

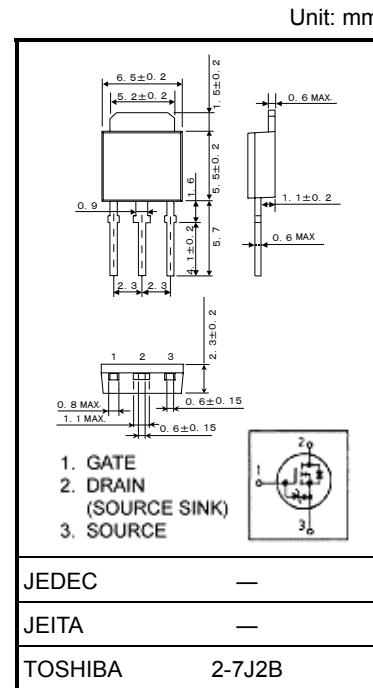
## Switching Applications

## Chopper Regulator, DC/DC Converter and Motor Drive Applications

- Low drain-source ON-resistance:  $R_{DS\ (ON)} = 1.6\ \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 2.0\ S$  (typ.)
- Low leakage current:  $I_{DSS} = -100\ \mu A$  (max) ( $V_{DS} = -200\ V$ )
- Enhancement model:  $V_{th} = -1.5 \sim -3.5\ V$  ( $V_{DS} = -10\ V$ ,  $I_D = -1\ mA$ )

## Maximum Ratings ( $T_a = 25^\circ C$ )

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	-200	V
Drain-gate voltage ( $R_{GS} = 20\ k\Omega$ )	$V_{DGR}$	-200	V
Gate-source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1)	$I_D$	A
	Pulse (Note 1)	$I_{DP}$	
Drain power dissipation ( $T_c = 25^\circ C$ )	$P_D$	20	W
Single pulse avalanche energy (Note 2)	$E_{AS}$	97.5	mJ
Avalanche current	$I_{AR}$	-2.5	A
Repetitive avalanche energy (Note 3)	$E_{AR}$	2.0	mJ
Channel temperature	$T_{ch}$	150	$^\circ C$
Storage temperature range	$T_{stg}$	-55~150	$^\circ C$



Weight: 0.36 g (typ.)

## Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	6.25	$^\circ C/W$
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	125	$^\circ C/W$

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = -50\ V$ ,  $T_{ch} = 25^\circ C$  (initial),  $L = -25.2\ mH$ ,  $I_{AR} = -2.5\ A$   $R_G = 25\ \Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

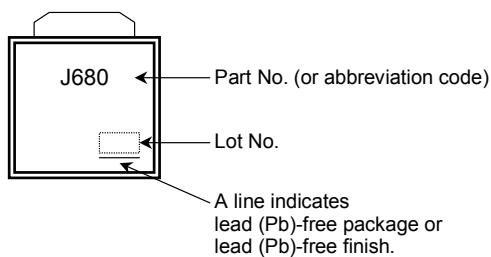
Electrical Characteristics ( $T_a = 25^\circ\text{C}$ )

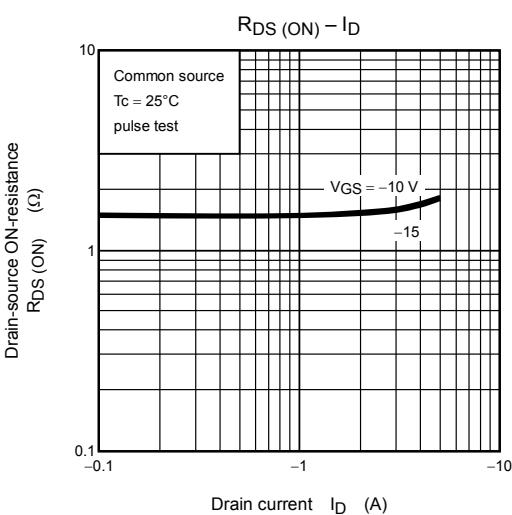
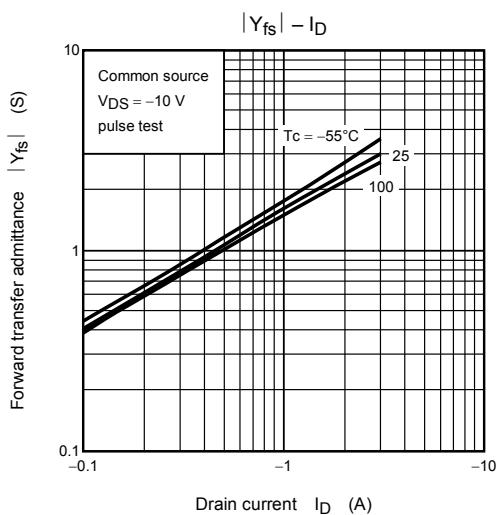
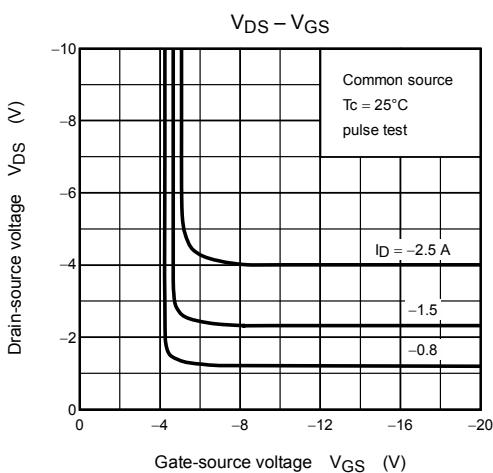
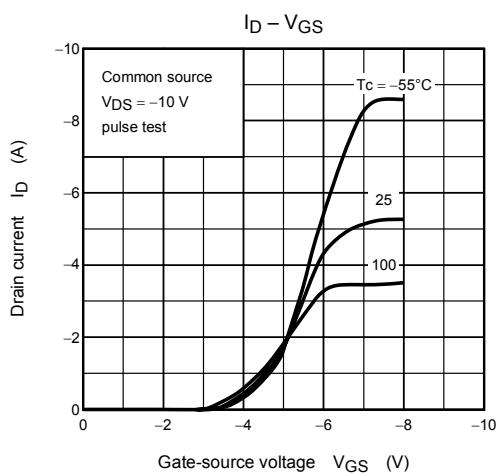
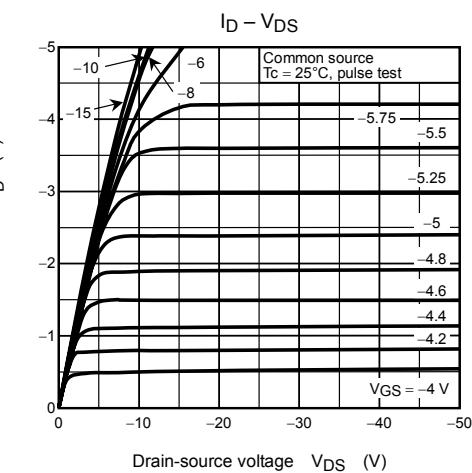
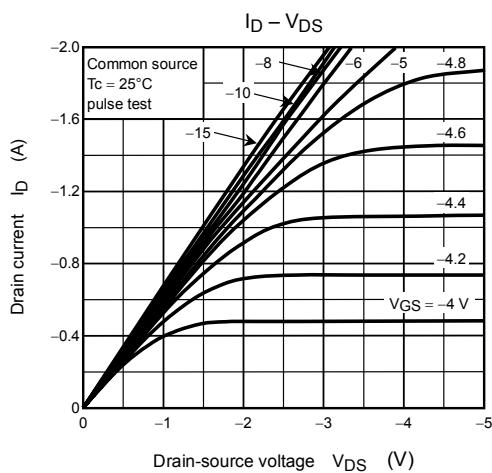
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cutoff current	$I_{DSS}$	$V_{DS} = -200\text{ V}, V_{GS} = 0\text{ V}$	—	—	-100	$\mu\text{A}$
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$I_D = -10\text{ mA}, V_{GS} = 0\text{ V}$	-200	—	—	V
Gate threshold voltage	$V_{th}$	$V_{DS} = -10\text{ V}, I_D = -1\text{ mA}$	-1.5	—	-3.5	V
Drain-source ON-resistance	$R_{DS(\text{ON})}$	$V_{GS} = -10\text{ V}, I_D = -1.5\text{ A}$	—	1.6	2.0	$\Omega$
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -10\text{ V}, I_D = -1.5\text{ A}$	1.0	2.0	—	S
Input capacitance	$C_{iss}$	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	410	—	pF
Reverse transfer capacitance	$C_{rss}$		—	40	—	
Output capacitance	$C_{oss}$		—	145	—	
Switching time	Rise time	$t_r$	 $V_{GS}$ (0 V to -10 V)	—	20	—
	Turn-on time	$t_{on}$		—	45	—
	Fall time	$t_f$		—	15	—
	Turn-off time	$t_{off}$		—	85	—
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} \approx -160\text{ V}, V_{GS} = -10\text{ V},$ $I_D = -2.5\text{ A}$	—	10	—	nC
Gate-source charge	$Q_{gs}$		—	6	—	
Gate-drain ("Miller") charge	$Q_{gd}$		—	4	—	

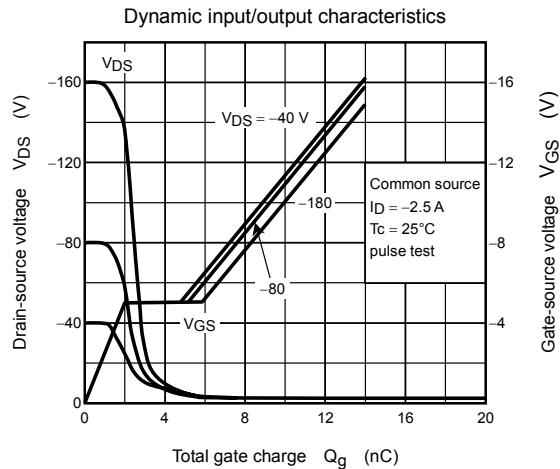
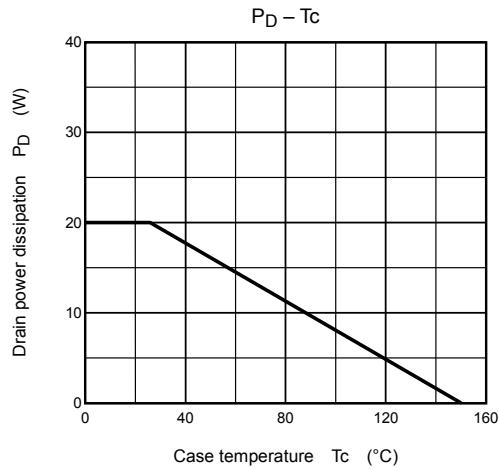
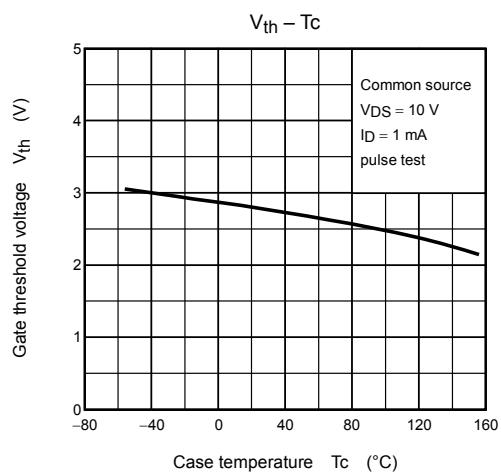
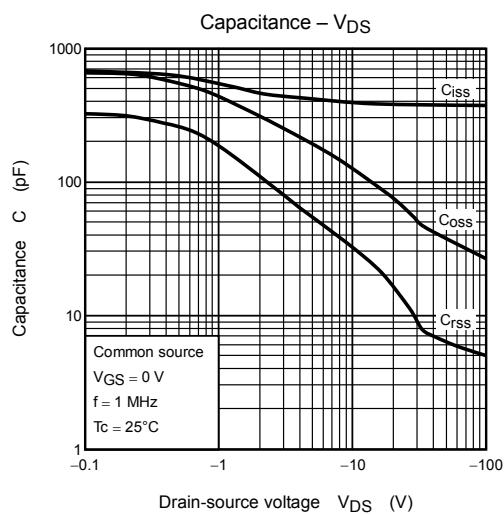
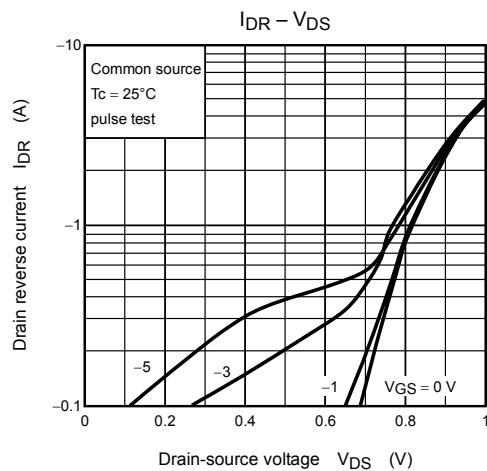
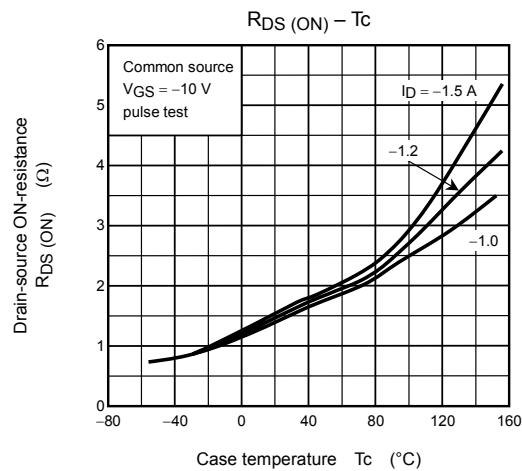
Source-Drain Ratings and Characteristics ( $T_a = 25^\circ\text{C}$ )

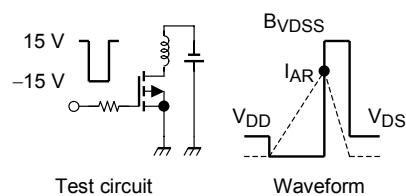
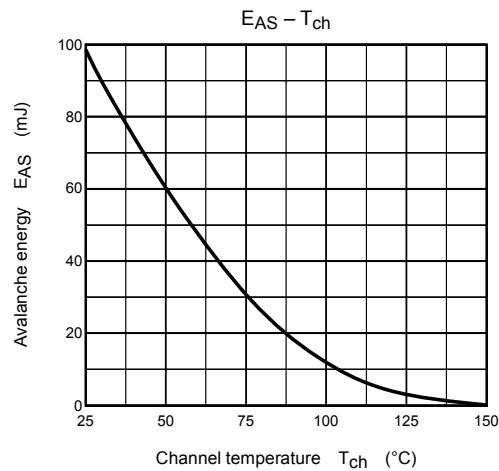
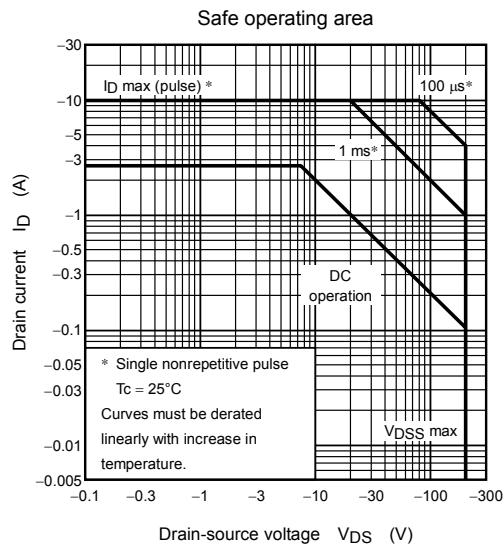
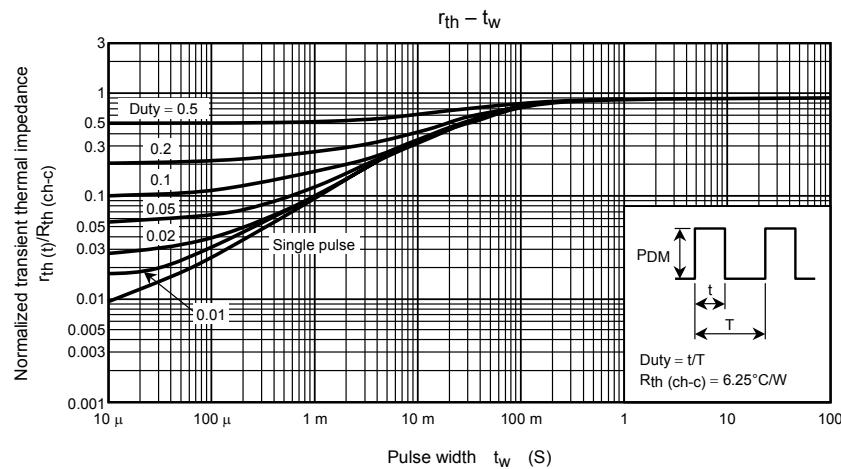
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	—	—	—	-2.5	A
Pulse drain reverse current (Note 1)	$I_{DRP}$	—	—	—	-10	A
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = -2.5\text{ A}, V_{GS} = 0\text{ V}$	—	—	2.0	V
Reverse recovery time	$t_{rr}$	$I_{DR} = -2.5\text{ A}, V_{GS} = 0\text{ V},$ $dI_{DR}/dt = 100\text{ A}/\mu\text{s}$	—	135	—	ns
Reverse recovery charge	$Q_{rr}$		—	0.81	—	$\mu\text{C}$

## Marking









$$R_G = 25 \Omega \quad V_{DD} = -50 \text{ V}, L = 25.2 \text{ mH} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$